

RTF016N05-VB Datasheet

N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^a	Q_g (Typ.)
60	0.075 at $V_{GS} = 10$ V	4.0	2.1 nC
	0.086 at $V_{GS} = 4.5$ V	3.8	

FEATURES

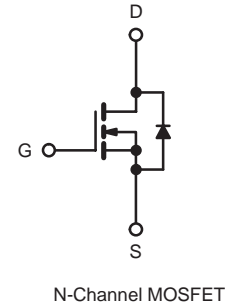
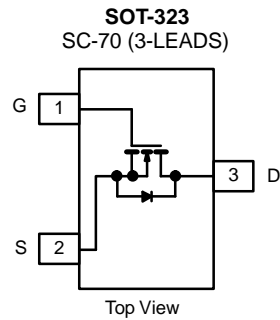
- Halogen-free According to IEC 61249-2-21 Available
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

APPLICATIONS

- Battery Switch
- DC/DC Converter



RoHS
COMPLIANT
HALOGEN
FREE
Available



ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$, unless otherwise noted

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	$T_C = 25^\circ\text{C}$	I_D	4.0	A
	$T_C = 70^\circ\text{C}$		3.4	
	$T_A = 25^\circ\text{C}$		3.1 ^{b, c}	
	$T_A = 70^\circ\text{C}$		2.5 ^{b, c}	
Pulsed Drain Current		I_{DM}	12	
Continuous Source-Drain Diode Current	$T_C = 25^\circ\text{C}$	I_S	1.39	
	$T_A = 25^\circ\text{C}$		0.91 ^{b, c}	
Avalanche Current	$L = 0.1$ mH	I_{AS}	6	mJ
Single-Pulse Avalanche Energy		E_{AS}	1.8	
Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	1.66	W
	$T_C = 70^\circ\text{C}$		1.06	
	$T_A = 25^\circ\text{C}$		1.09 ^{b, c}	
	$T_A = 70^\circ\text{C}$		0.7 ^{b, c}	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	≤ 5 s	R_{thJA}	90	115	$^\circ\text{C/W}$
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	60	75	

Notes:

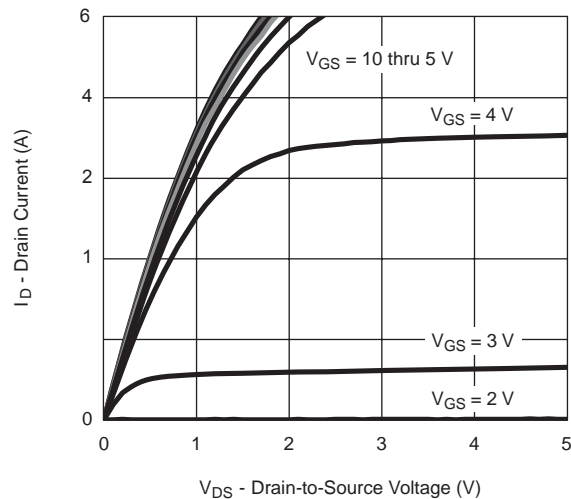
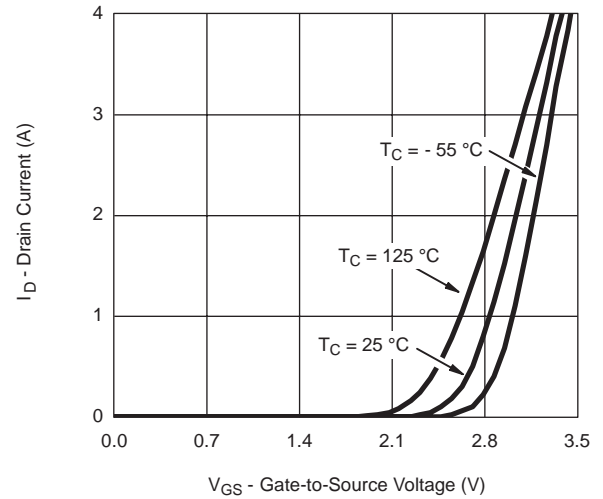
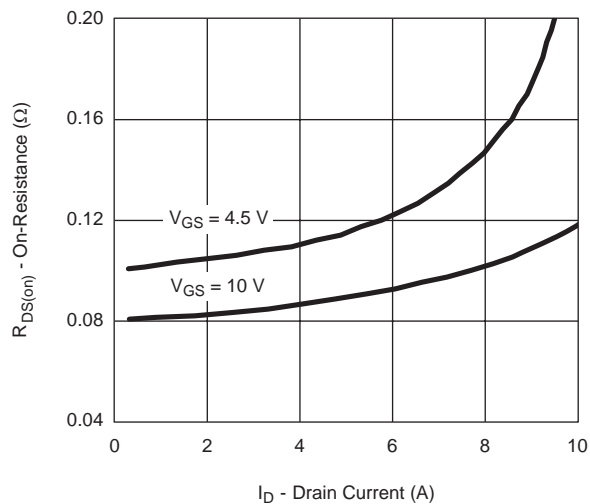
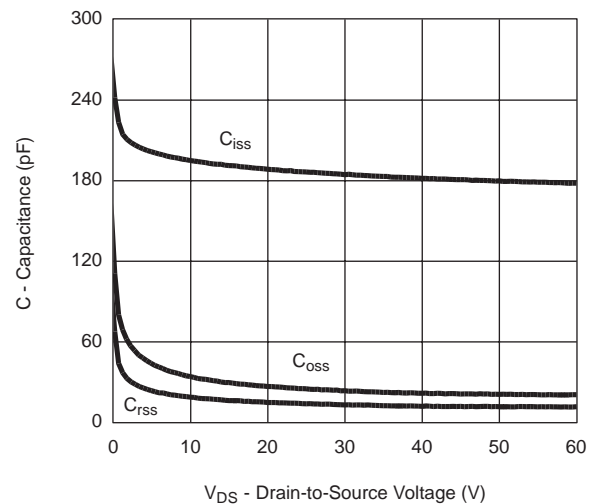
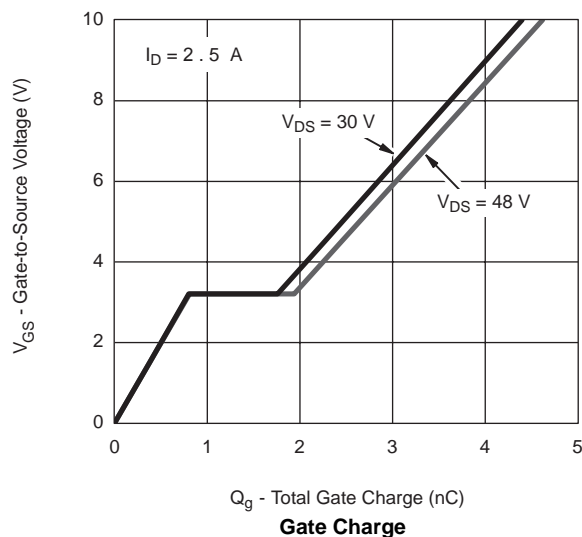
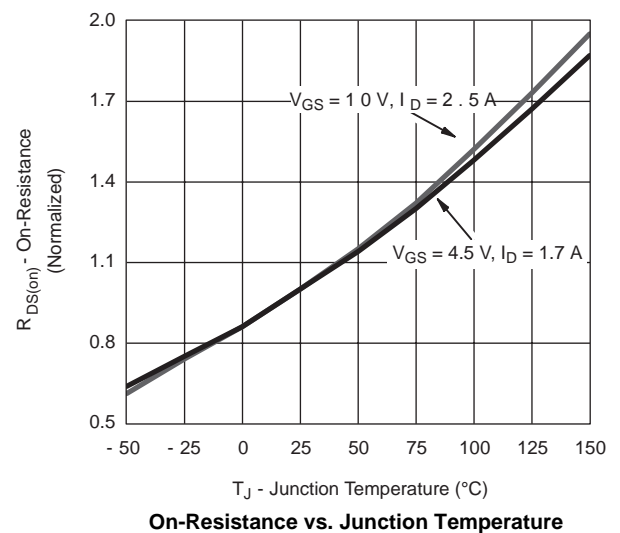
- Based on $T_C = 25^\circ\text{C}$.
- Surface Mounted on 1" x 1" FR4 board.
- $t = 5$ s.
- Maximum under Steady State conditions is 120°C/W .

MOSFET SPECIFICATIONS T _J = 25 °C, unless otherwise noted								
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit		
Static								
Drain-Source Breakdown Voltage	V _{DS}	V _{DS} = 0 V, I _D = 250 μA	60			V		
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μA		55		mV/°C		
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			- 5				
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1		3	V		
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V			1	μA		
		V _{DS} = 60 V, V _{GS} = 0 V, T _J = 55 °C			10			
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	8			A		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 1.9 A		0.075		Ω		
		V _{GS} = 4.5 V, I _D = 1.7 A		0.086				
Forward Transconductance ^a	g _{fs}	V _{DS} = 15V, I _D = 1.9 A		5		S		
Dynamic ^b								
Input Capacitance	C _{iss}	V _{DS} = 30 V, V _{GS} = 0 V, f = 1 MHz		180		pF		
Output Capacitance	C _{oss}			22				
Reverse Transfer Capacitance	C _{rss}			13				
Total Gate Charge	Q _g	V _{DS} = 30 V, V _{GS} = 10 V, I _D = 1.9 A		4.2	6.1	nC		
		V _{DS} = 30 V, V _{GS} = 4.5 V, I _D = 1.9 A		2.1	3.2			
Gate-Source Charge	Q _{gs}			0.7				
Gate-Drain Charge	Q _{gd}			1				
Gate Resistance	R _g	f = 1 MHz	0.6	2.2	5.1	Ω		
Turn-On Delay Time	t _{d(on)}	V _{DD} = 30 V, R _L = 20 Ω I _D ≅ 1.5 A, V _{GEN} = 10 V, R _G = 1 Ω		4	6	ns		
Rise Time	t _r			10	15			
Turn-Off Delay Time	t _{d(off)}			10	15			
Fall Time	t _f			7	10.5			
Turn-On Delay Time	t _{d(on)}	V _{DD} = 30 V, R _L = 20 Ω I _D = 1.5 A, V _{GEN} = 4.5 V, R _G = 1 Ω		15	23	ns		
			Rise Time	t _r			16	24
			Turn-Off Delay Time	t _{d(off)}			11	17
			Fall Time	t _f			11	17
Drain-Source Body Diode Characteristics								
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			2.19	A		
Pulse Diode Forward Current ^a	I _{SM}				7			
Body Diode Voltage	V _{SD}	I _S = 1.5 A		0.8	1.2	V		
Body Diode Reverse Recovery Time	t _{rr}	I _F = 1.5 A, dI/dt = 100 A/μs, T _J = 25 °C		15	23	ns		
Body Diode Reverse Recovery Charge	Q _{rr}			10	15	nC		
Reverse Recovery Fall Time	t _a			12		ns		
Reverse Recovery Rise Time	t _b			3				

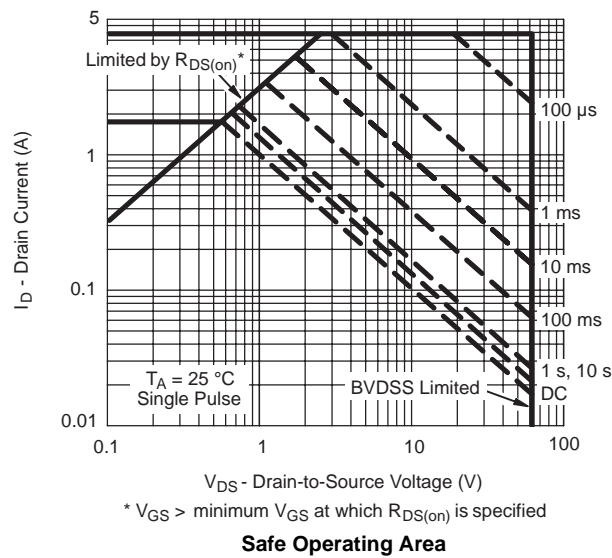
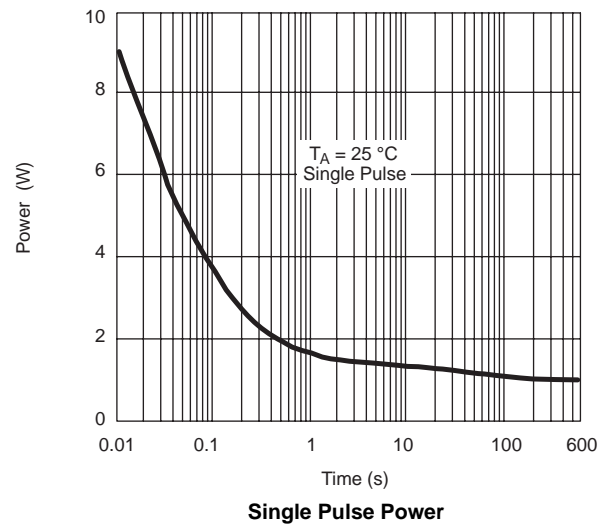
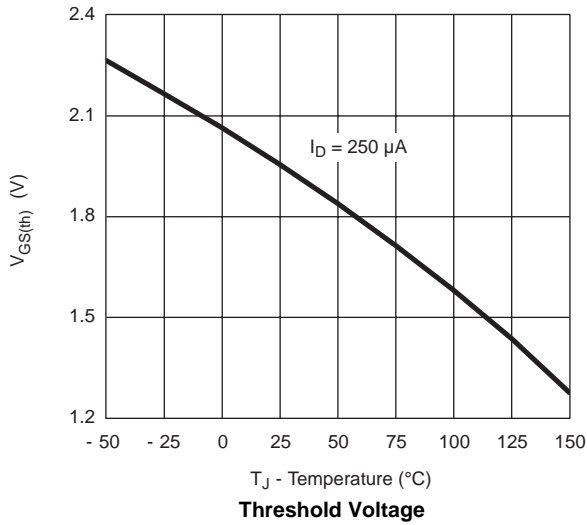
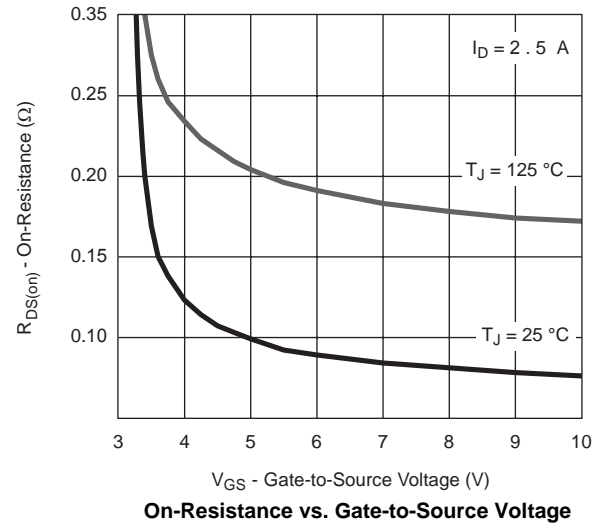
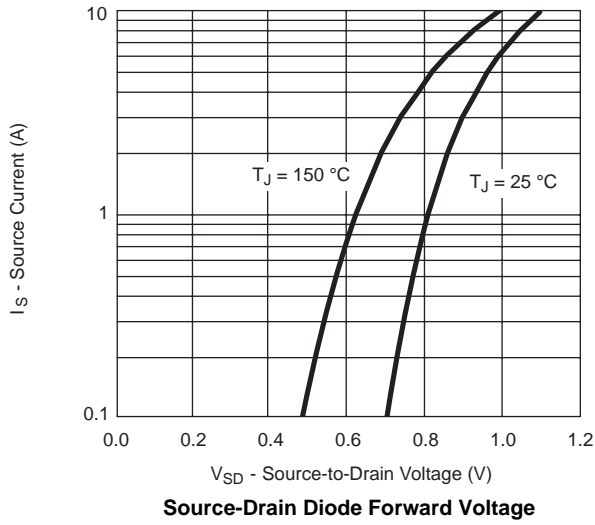
Notes:

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
 b. Guaranteed by design, not subject to production testing.

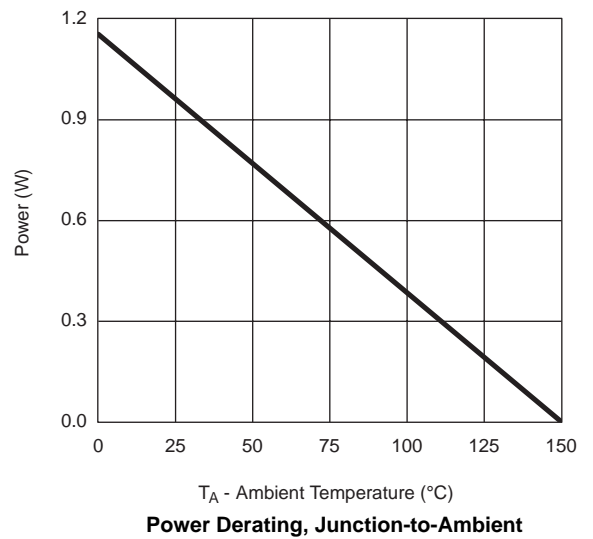
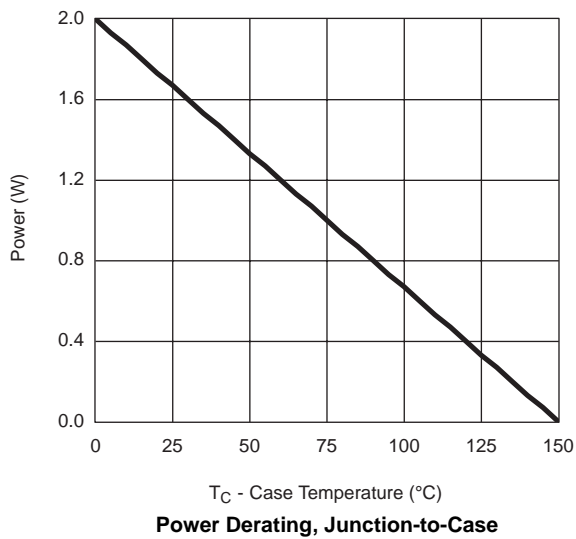
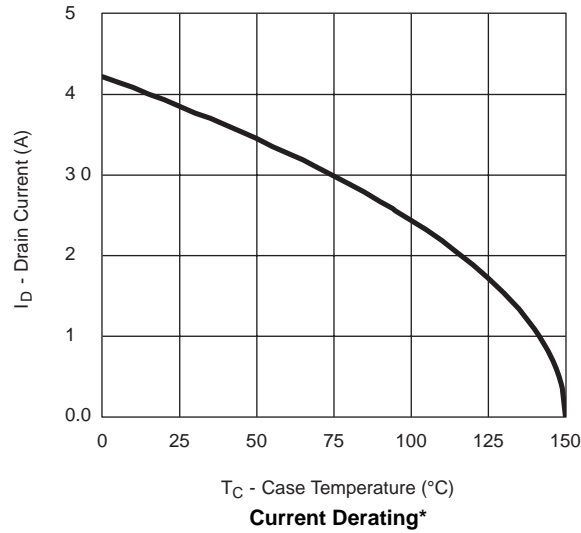
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Output Characteristics

Transfer Characteristics

On-Resistance vs. Drain Current and Gate Voltage

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

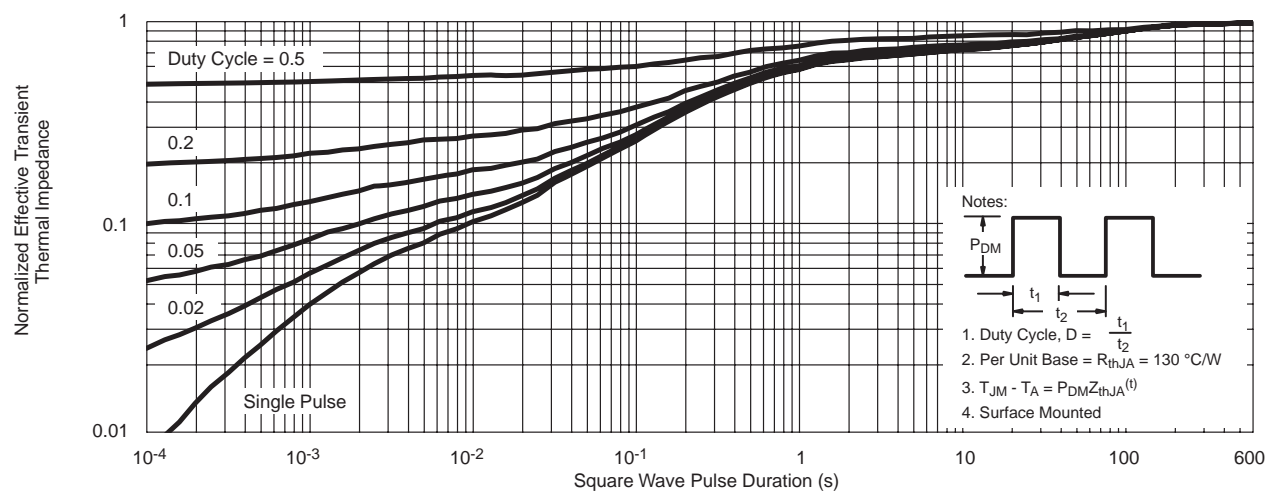


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

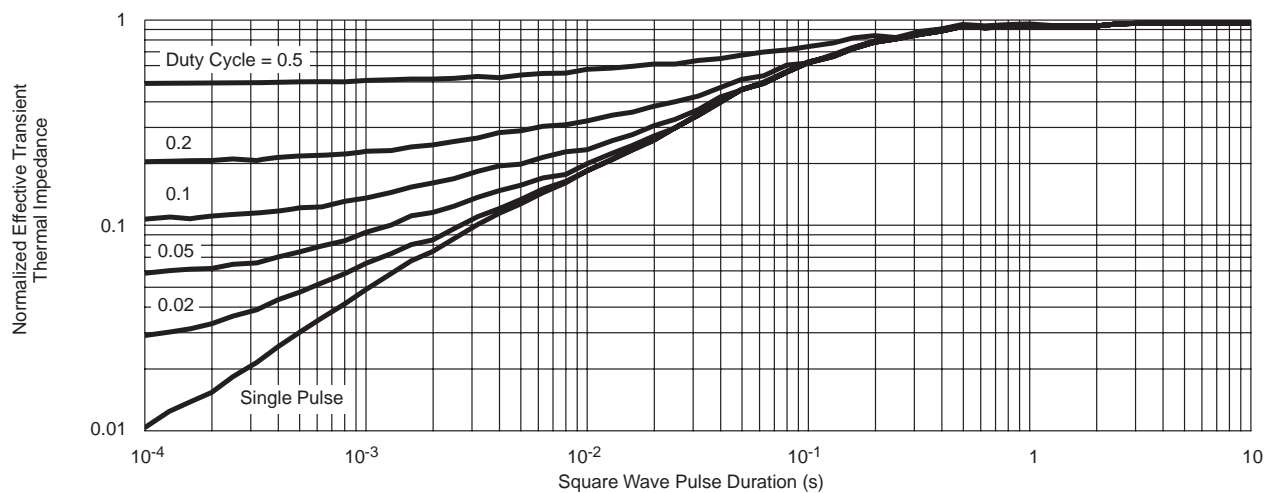


* The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

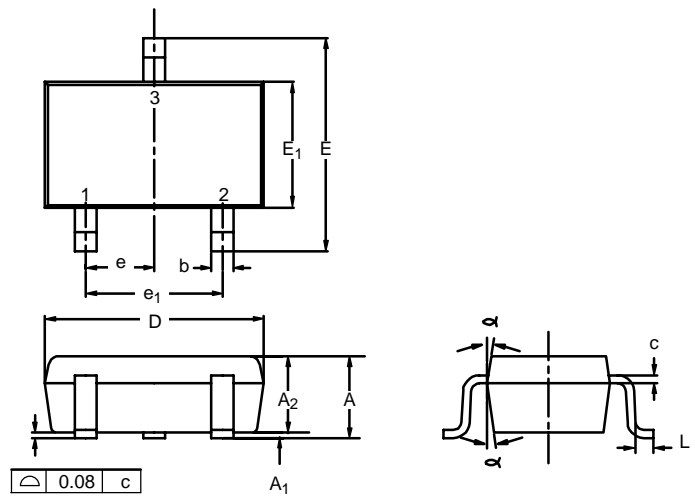


Normalized Thermal Transient Impedance, Junction-to-Ambient



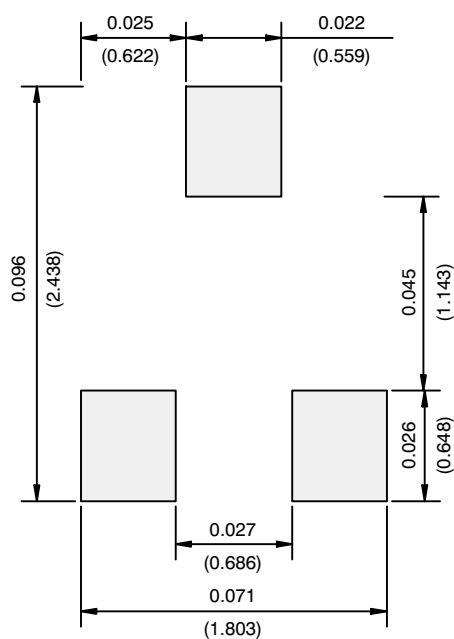
Normalized Thermal Transient Impedance, Junction-to-Foot

SC-70: 3-LEADS



Dim	MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max
A	0.90	—	1.10	0.035	—	0.043
A ₁	—	—	0.10	—	—	0.004
A ₂	0.80	—	1.00	0.031	—	0.039
b	0.25	—	0.40	0.010	—	0.016
c	0.10	—	0.25	0.004	—	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
E	1.80	2.10	2.40	0.071	0.083	0.094
E ₁	1.15	1.25	1.35	0.045	0.049	0.053
e	0.65BSC			0.026BSC		
e ₁	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
α	7°Nom			7°Nom		
ECN: S-03946—Rev. C, 09-Jul-01 DWG: 5549						

RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

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